

Board Level Cooling – Surface Mount 5733



BOARD LEVEL COOLING – Surface Mount 5733

Surface Mount 5733 is a series of surface mount board level heat sinks designed to cool Dual Flat No-Leads (DFN) packages, Quad Flat No-Leads (QFN) packages and D2 Pak (TO-263) devices. Surface Mount 5733 can cool either a single D2 Pak, larger QFNs or DFNs, or multiple QFNs or DFNs. The tin plated surface of Surface Mount 5733 enables direct soldering to Printed Circuit Boards (PCBs) for effective board cooling.

573300D00000G is the bulk packaging option of Surface Mount 5733 and 573300D00010G is the tape and reel offering for high volume manufacturing. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
573300D00000G	QFN, DFN, D2 Pak, TO-263
573300D00010G	QFN, DFN, D2 Pak, TO-263

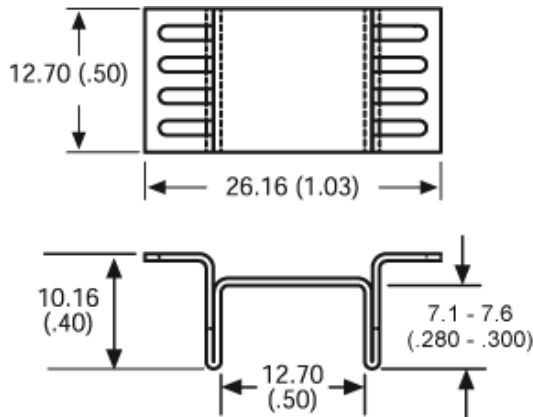
HEAT SINK DETAILS

Property	Details
Material	Copper
Finish	Tin Plated
Device Attachment Options	-
Thermal Interface Material	-

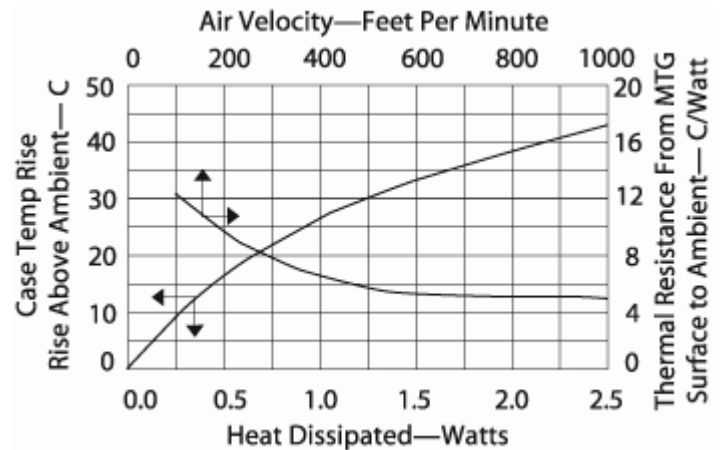
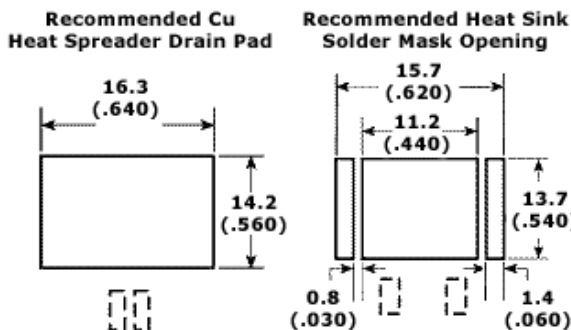
Property	Details
Heat Sink Width (mm)	26.16
Heat Sink Length (mm)	12.70
Heat Sink Height (mm)	10.16
Heat Sink Mounting Direction	Horizontal

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)



Note: The thickness of the drain pad is variable depending on the amount of heat generated by the SMT device, design, limitations and process. This is the exposed printed circuit.



USA: 1.855.322.2843
EUROPE: 39.051.764002
ASIA: 86.21.6115.2000 x8122